Title (en)

ALLOY C11004

Title (de)

C11004 LEGIERUNG

Title (fr)

ALLIAGE C11004

Publication

**EP 0866883 A4 19981223 (EN)**

Application

**EP 97905859 A 19970207**

Priority

- US 9702030 W 19970207
- US 59961296 A 19960209

Abstract (en)

[origin: WO9729216A1] An enhanced bonding copper alloy characterized by an oxygen content generally within a range of 350 ppm to 709 ppm, an iron content generally less than about 20 ppm, a zinc content generally less than about 24 ppm, a silicon content generally less than about 31 ppm, generally less than about 31 ppm aluminum, a tin content generally less than about 10 ppm, generally less than about 10 ppm lead and about 10 ppm magnesium, a manganese content generally less than about 10 ppm, generally less than about 10 ppm cobalt, generally less than about 31 ppm nickel, and a cadmium content generally less than about 10 ppm, the balance copper.

IPC 1-7

**C22C 9/00**

IPC 8 full level

**C22C 9/00** (2006.01)

CPC (source: EP)

**C22C 9/00** (2013.01)

Citation (search report)

- [X] EP 0667640 A2 19950816 - BRUSH WELLMAN [US]
- [X] GB 2012813 A 19790801 - SUMITOMO ELECTRIC INDUSTRIES
- [PXD] US 5583317 A 19961210 - MENNUCCI JOSEPH P [US], et al
- [X] PATENT ABSTRACTS OF JAPAN vol. 012, no. 164 (M - 698) 18 May 1988 (1988-05-18)
- [X] PATENT ABSTRACTS OF JAPAN vol. 010, no. 120 (C - 343) 6 May 1986 (1986-05-06)
- [X] DATABASE WPI Section Ch Week 8637, Derwent World Patents Index; Class M23, AN 86-241414, XP002082016
- [X] DATABASE WPI Section Ch Week 8228, Derwent World Patents Index; Class L03, AN 82-58018E, XP002082017
- See references of WO 9729216A1

Designated contracting state (EPC)

AT BE CH DE DK ES FI FR GB GR IE IT LI LU MC NL PT SE

DOCDB simple family (publication)

**WO 9729216 A1 19970814**; EP 0866883 A1 19980930; EP 0866883 A4 19981223

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